

Exploiting Emerging Memory Technologies for Hardware Security

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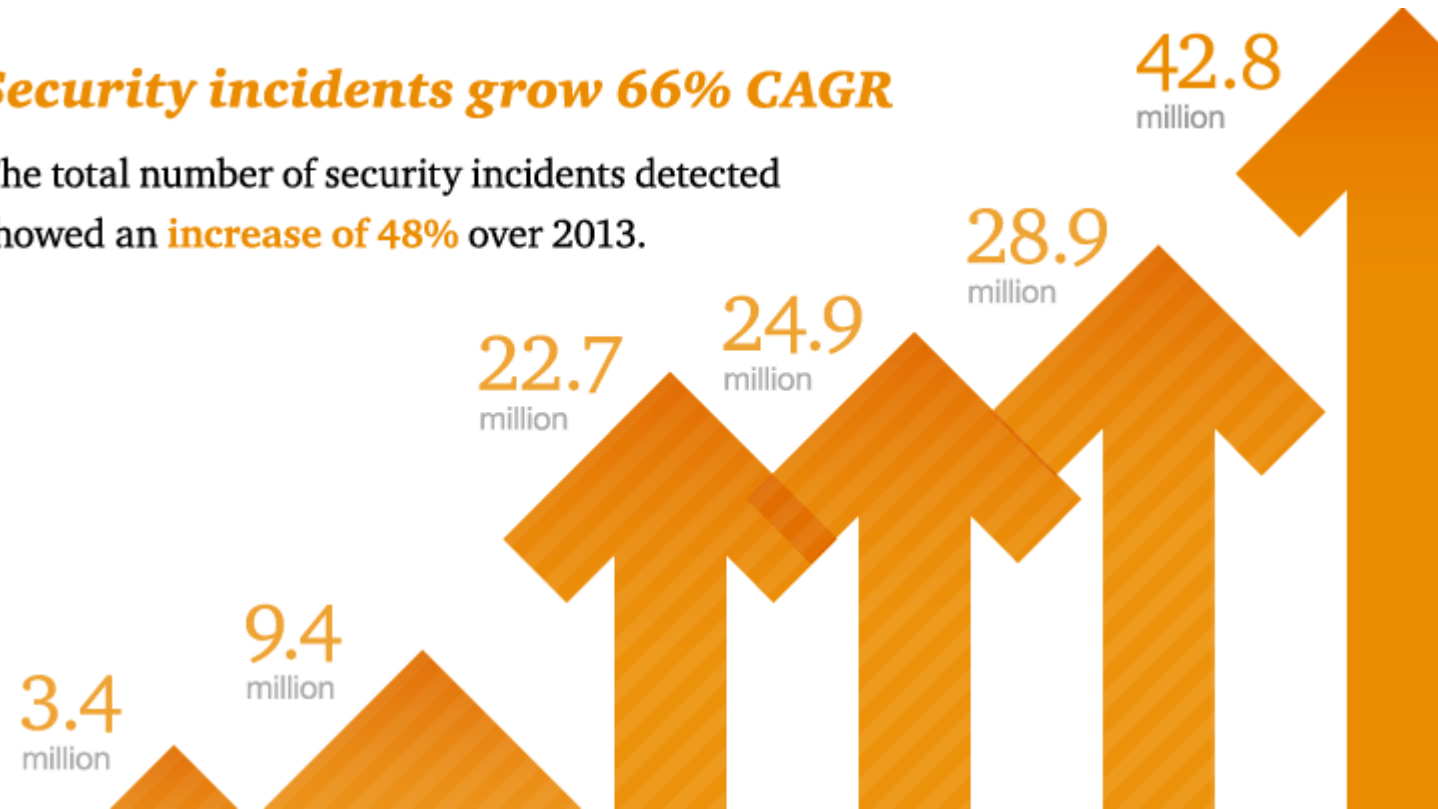
PennState

Lab of Green & Secure Integrated Circuit Systems (LOGICS)

Why We Should Care?

Security incidents grow 66% CAGR

The total number of security incidents detected showed an **increase of 48%** over 2013.



The New Trend

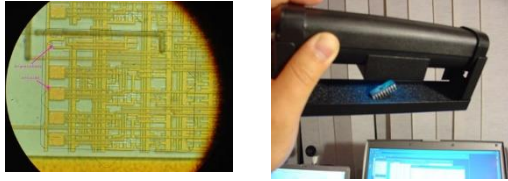
- Software level security policies assume hardware to be secure
 - Not the case anymore

Cyber threats seek greater control and opportunities further down the stack.



Motivational Examples

Hacking PIC uC



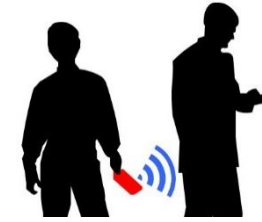
Vulnerability: UV-EPROM

Hacking Apple battery



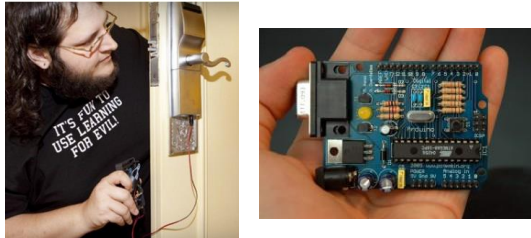
Vulnerability: hardcoded passwords

RFID snooping&cloning



Vulnerability: unencrypted communication

Hacking hotel key



Vulnerability: unprotected key

Hacking smart meter



Vulnerability: unprotected key

Outline

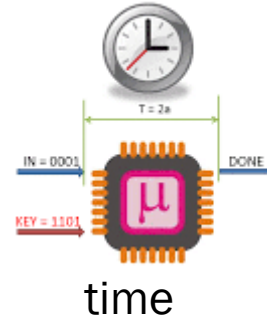
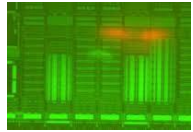
- Basics of hardware security
- CMOS security primitives
- Emerging technologies
- Application in security
- Conclusions

Side Channel Attacks

Voltage, current

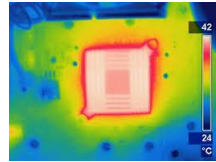


light

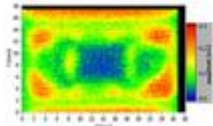


time

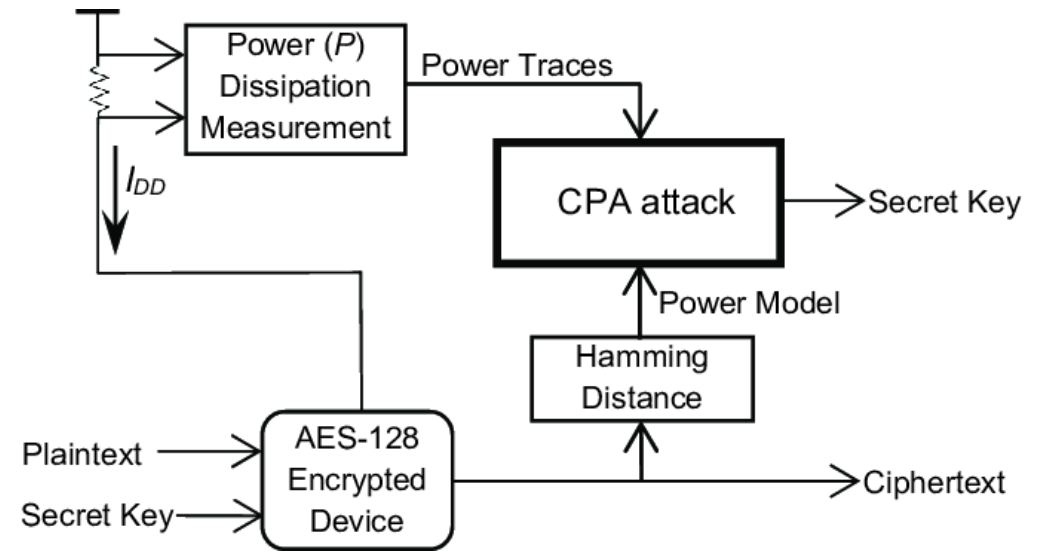
heat



EM

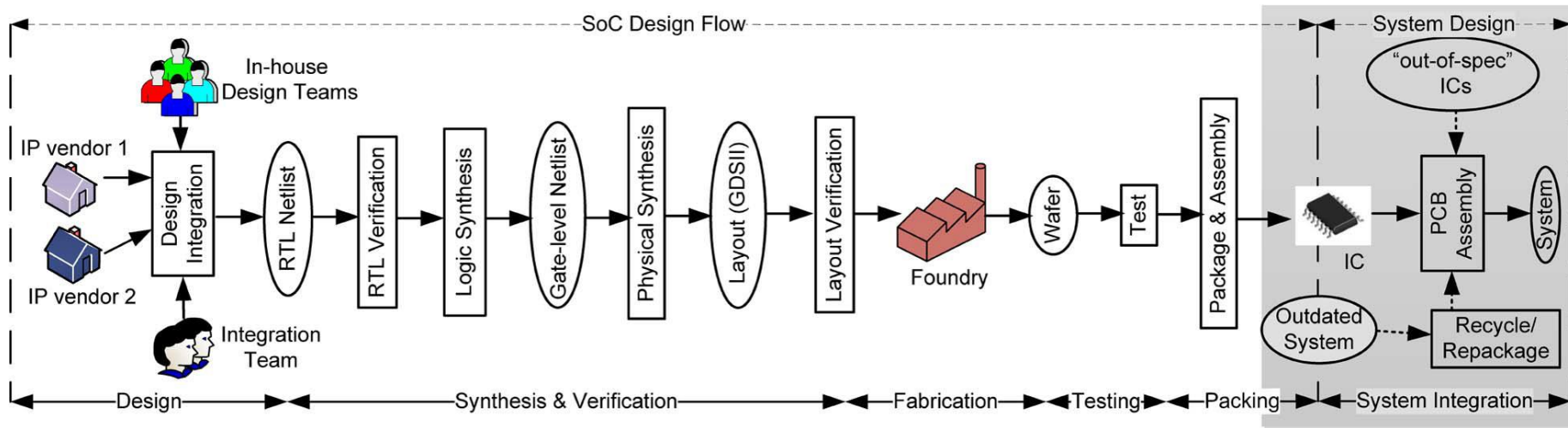


sound



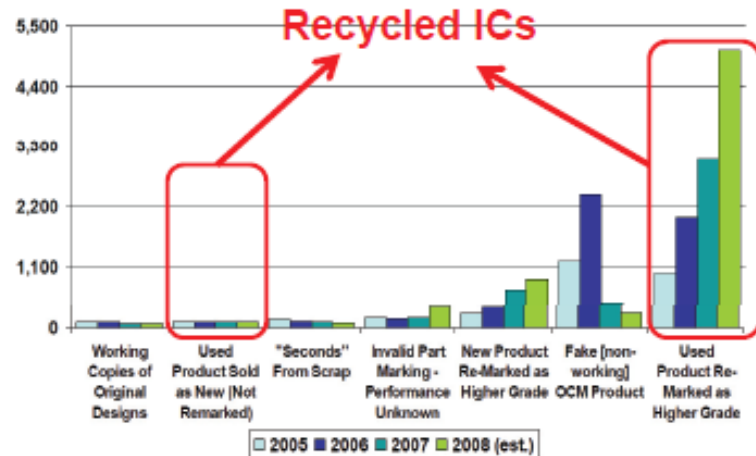
- Possible sources: electrical, ambient, acoustical, temporal...
- Objective: extract valuable information

Semiconductor Supply Chain



- Profit driven business model that relies on outsourcing
 - Security vulnerabilities present at many stages of design and manufacturing process
- Attacks
 - Counterfeiting
 - Hardware Trojan Horses
 - Cloning
 - Overproduction
 - Reverse engineering
 - Non-invasive tampering

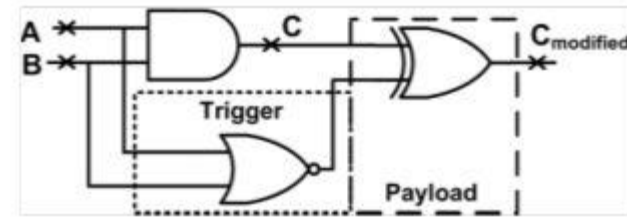
IC Recycling/Counterfeiting



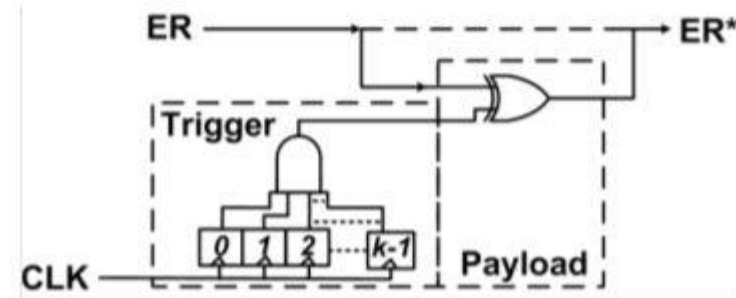
Hardware Trojans



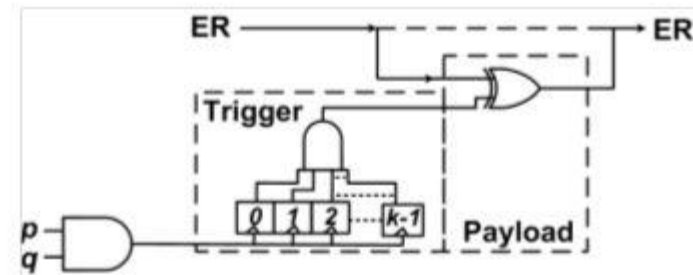
- Undesirable/ unintended design features to
 - Bypass security features
 - Bypasses convention test methods
 - Triggers in-field failures



(a) Combinationally triggered Trojan

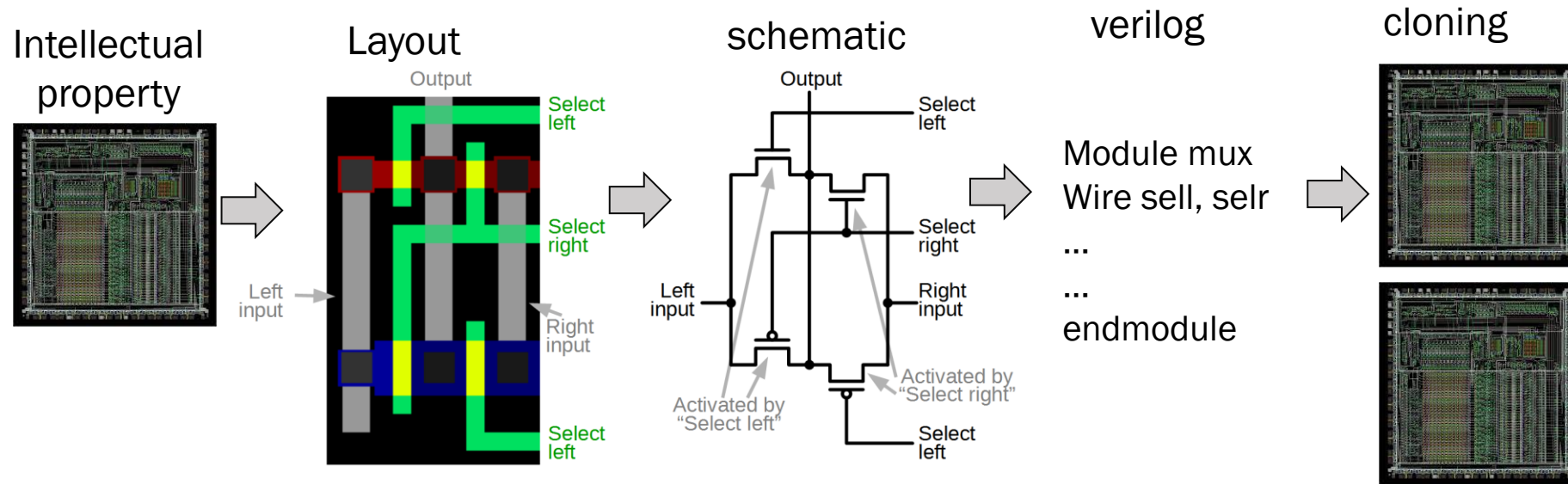


(b) Synchronous counter ("time-bomb") Trojan



(c) Asynchronous counter Trojan

Reverse Engineering and Cloning



- Delayering of chip, identification of gates and their connectivity information, and, reconstruction of netlist
 - Goals: competitive analysis, cloning and overproduction, siphoning profit

Non-Invasive Tampering

laser



X-ray gun



magnet



UV light



heat



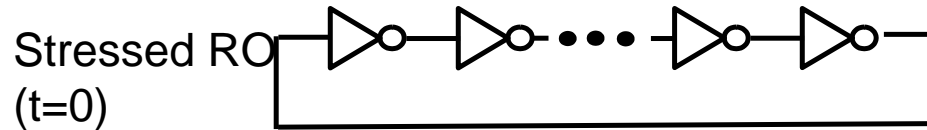
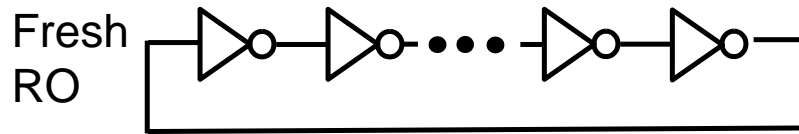
Ion gun

- Objective is to
 - Bypass security features
 - Launch denial-of-service attack
 - Extract valuable information

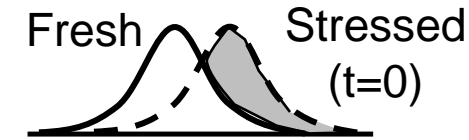
Outline

- Basics of hardware security
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- Emerging technologies
- Application in security
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Recycling Sensor



Case-1



Shaded chips are flagged recycled

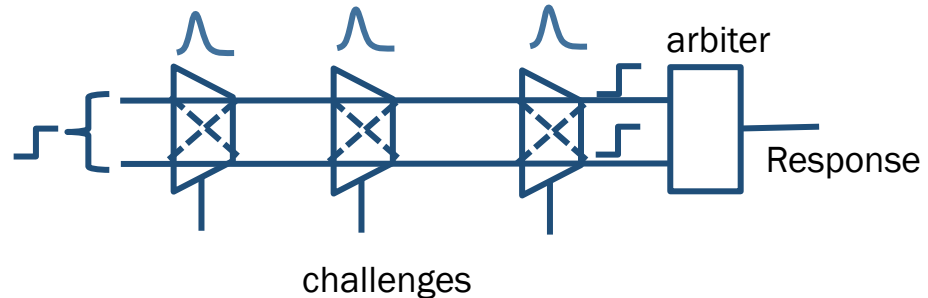
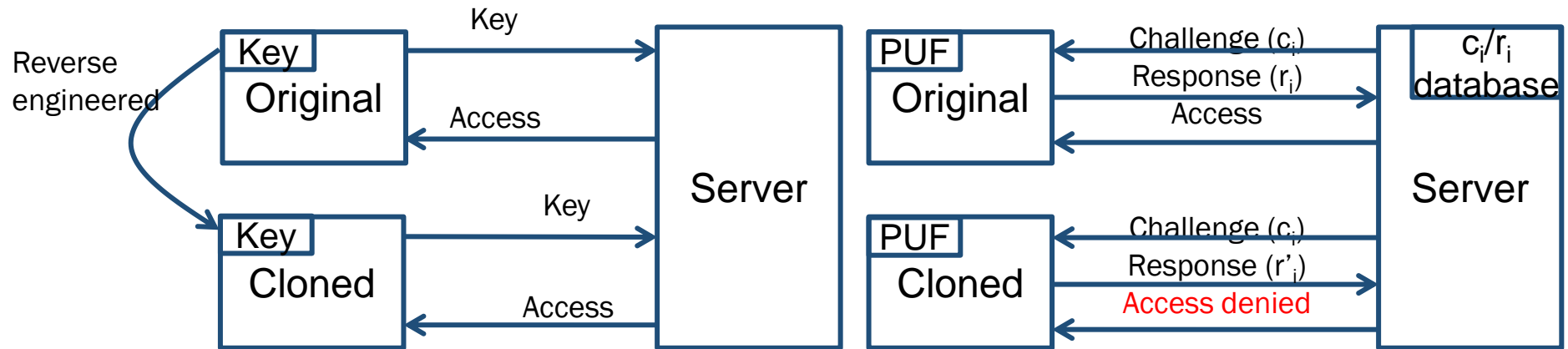
Case-2



Recycling of shaded chips are masked

- Aged RO is compared with fresh RO
- Challenges
 - Process variation results in wrong decision or masking
 - Limited by aging of RO and delay sensitivity of RO on aging
- Prevents recycling/counterfeit ICs

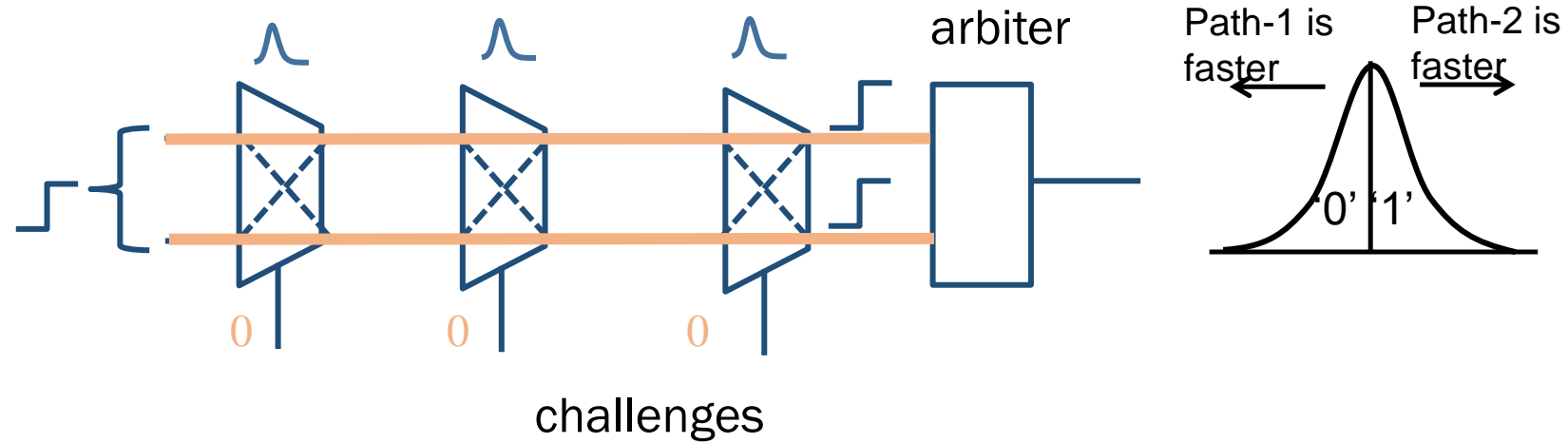
Physically Unclonable Functions



Process variation results in unique die-to-die response

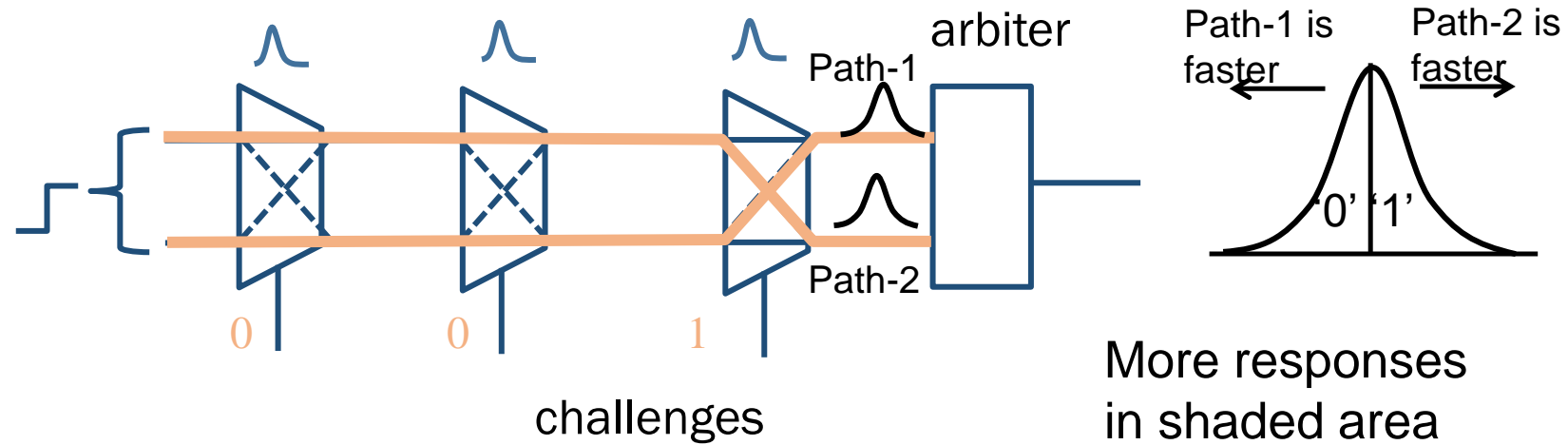
- PUF replaces the hardcoded key with a challenge response system
 - Response is generated from physical properties of the chip
 - Cannot be cloned
- Prevents cloning, counterfeit IC

Physically Unclonable Functions

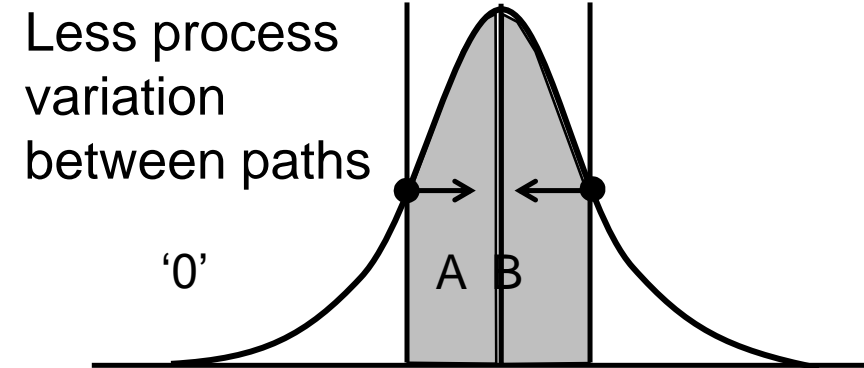


- Different chips produce different responses for same challenge

Physically Unclonable Functions

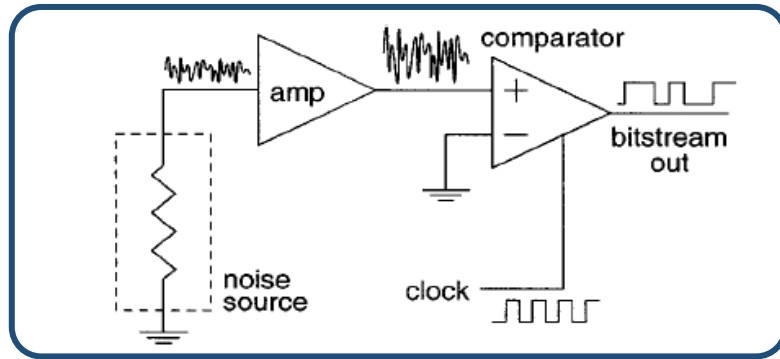


- Process variation is good

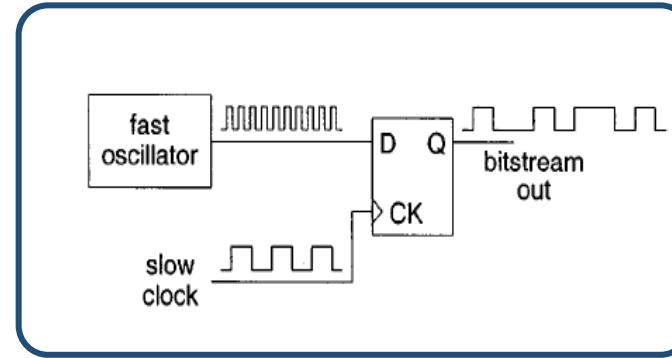


True Random Number Generator

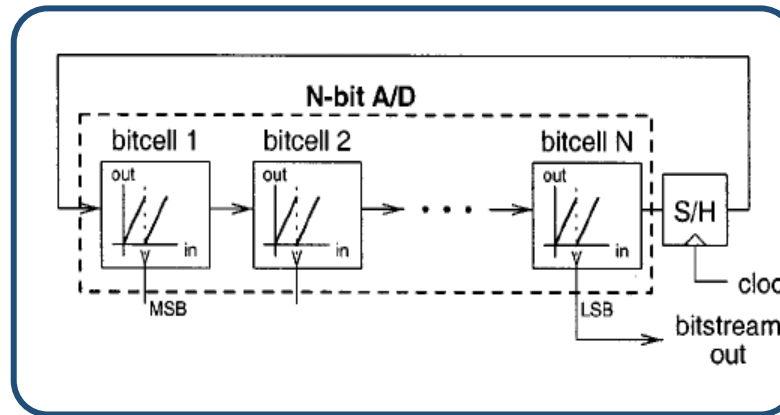
Direct amplification



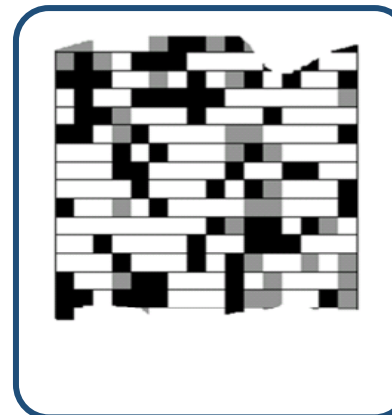
Oscillator sampling



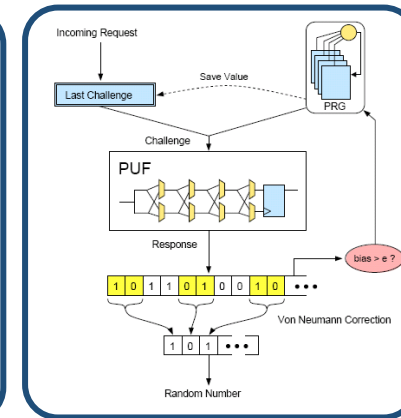
Discrete time chaos



SRAM PUF



PUF

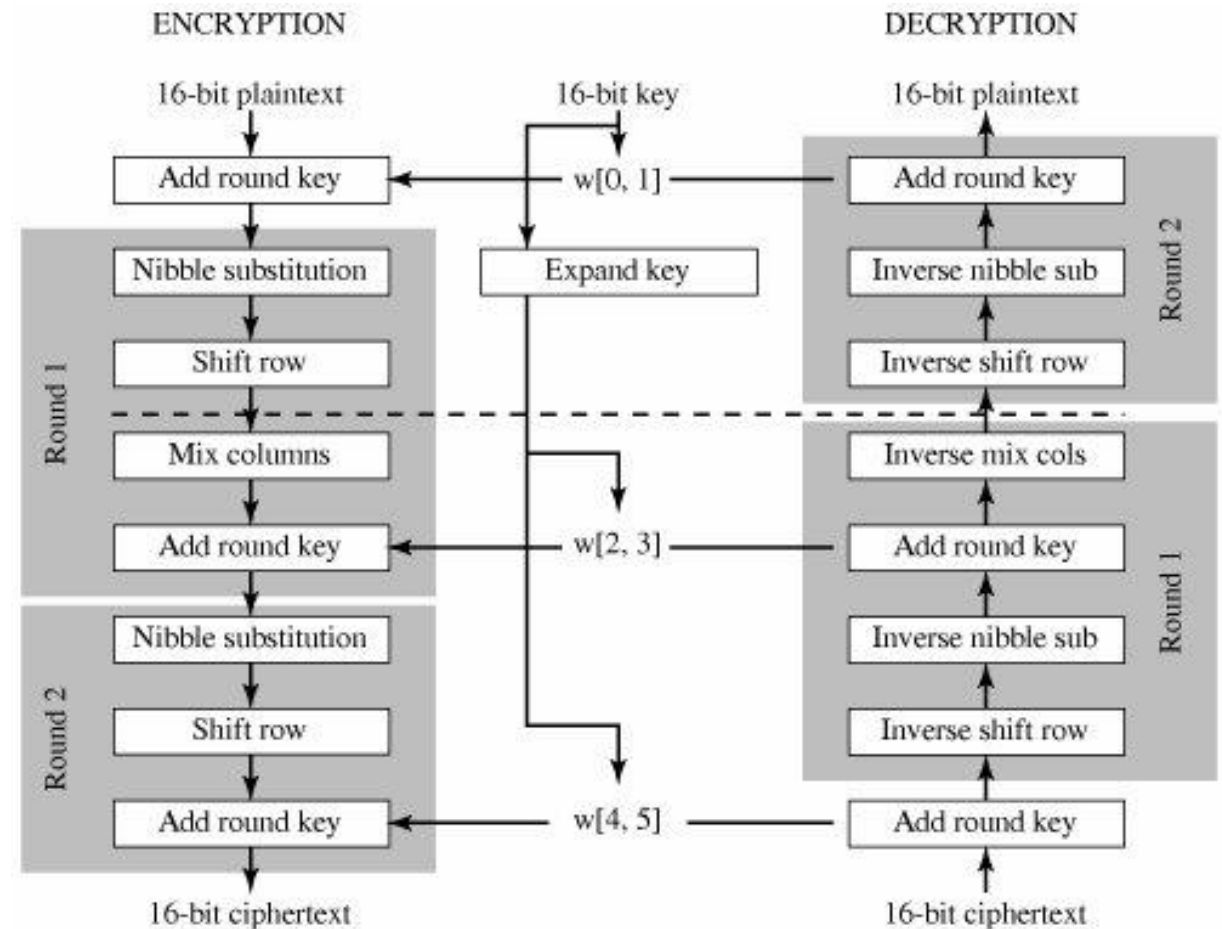


- Key generation and seed generation for authentication, secure communication



Encryption Engines

- Ensures privacy in communication
- Requires extensive shift, XOR and addition operation
 - Prone to side channel attack



Hardware Security Primitives- Key Requirements

Security primitive	Key Requirements
Recycling sensor	Low process variation, high sensitivity to usage
PUF	High process variation, nonlinearity
TRNG	High entropy
Encryption	Recursive shift, multiplication, addition
Miscellaneous	Sensitivity to ambient parameters

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Emerging Technologies

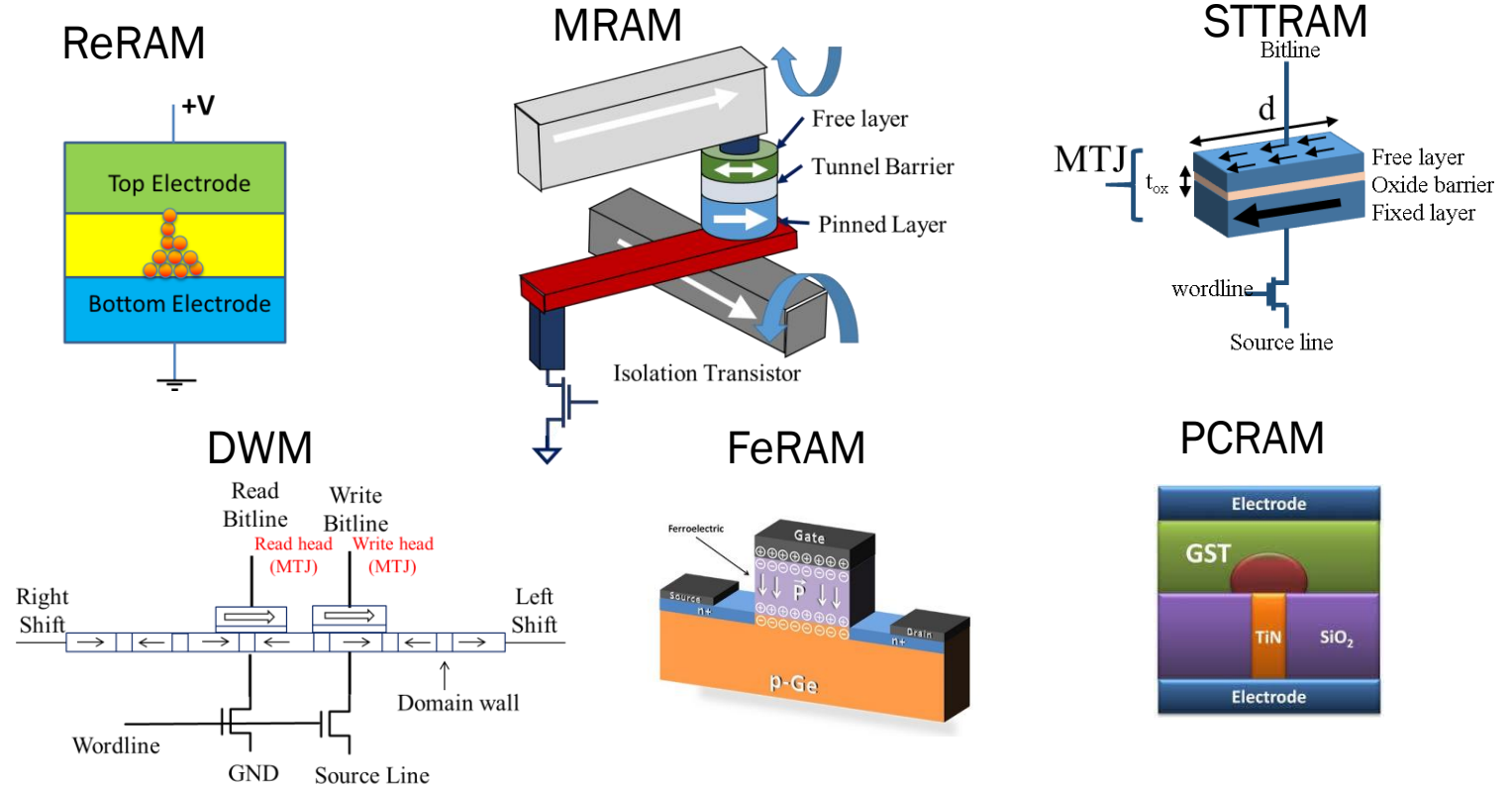
- Opportunities

- Non-volatility, electroforming, asymmetric read/write, retention, magnetization noise, stochastic resistance, non-linearity, random DW dynamics...

- Challenges

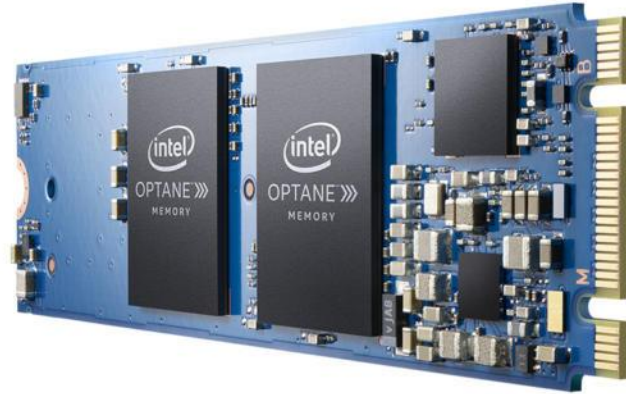
- Vulnerabilities

- Need deeper understanding for right application



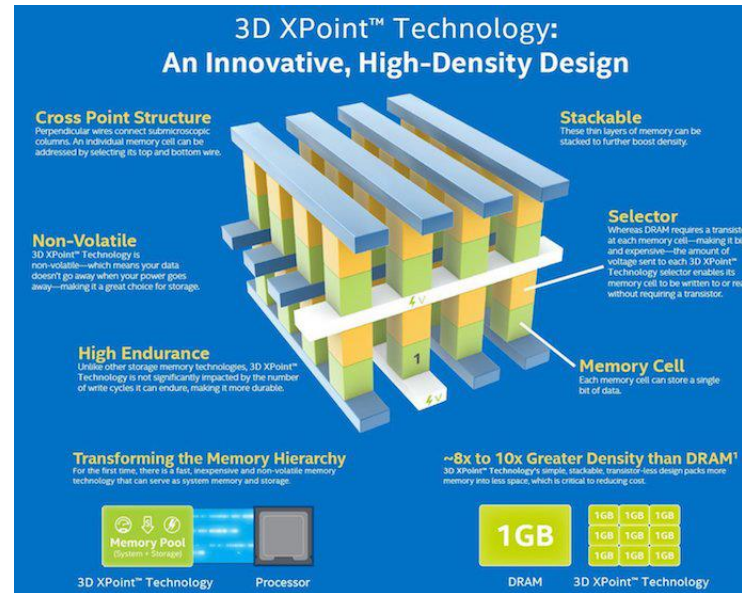
Recent Commercialization of Emerging NVMs

Phase Change RAM*

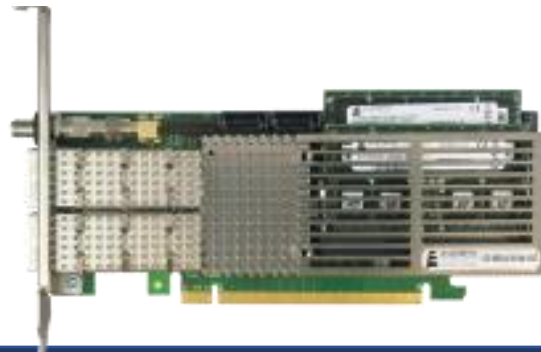


Intel unveils its Optane hyperfast memory

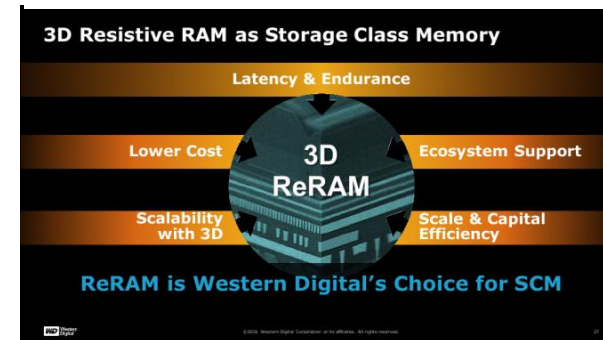
Intel released few key details around its new non-volatile memory



STT- MRAM



ReRAM



Western Digital to Use 3D ReRAM as Storage Class Memory for Special-Purpose SSDs

by Anton Shilov on August 12, 2016 8:00 AM EST



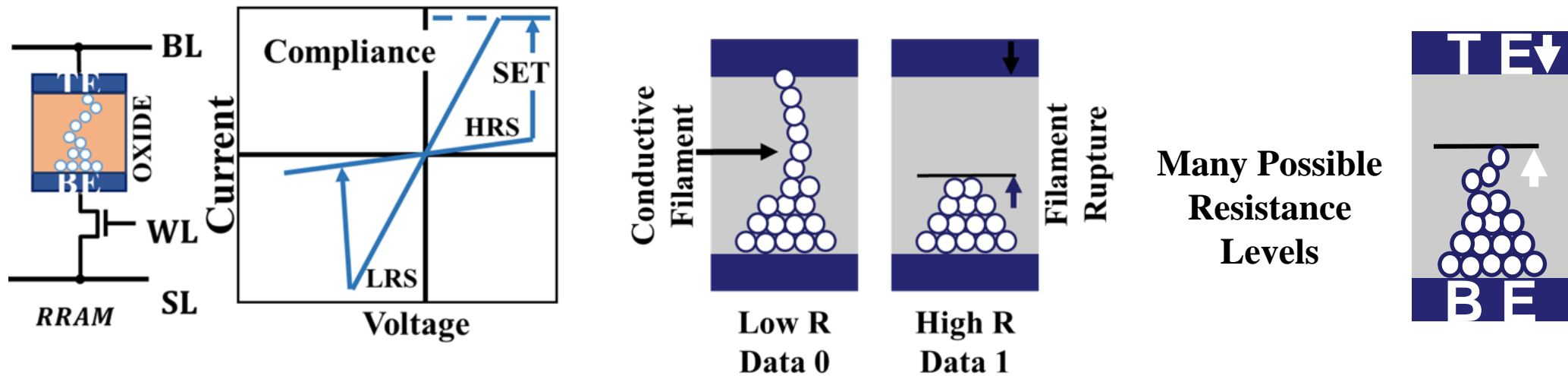
Penn

Published: March 9, 2017

Everspin unveils a new low latency, PCIe NVMe card based on Spin Torque MRAM

NVM: Resistive RAM (ReRAM)

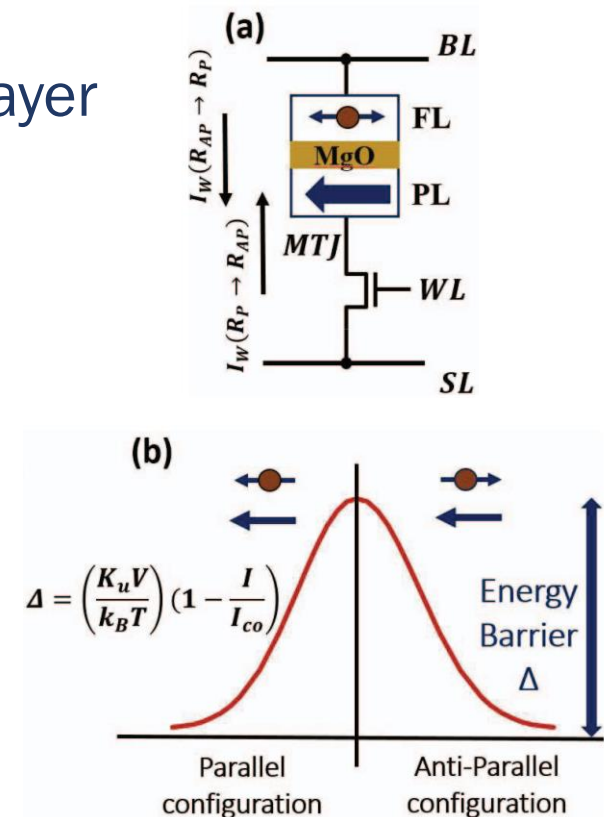
- ReRAM Features
 - Bits stored as resistance state
 - Low R → Data “0”, High R → Data “1”
 - Possible Oxides: HfO_2 , TiO_2 , TaO_x , WO_x
- Offers lowest footprint ($4F^2$ for xpoint)



NVM: Spin Torque Transfer RAM (STTRAM)

- STTRAM Features

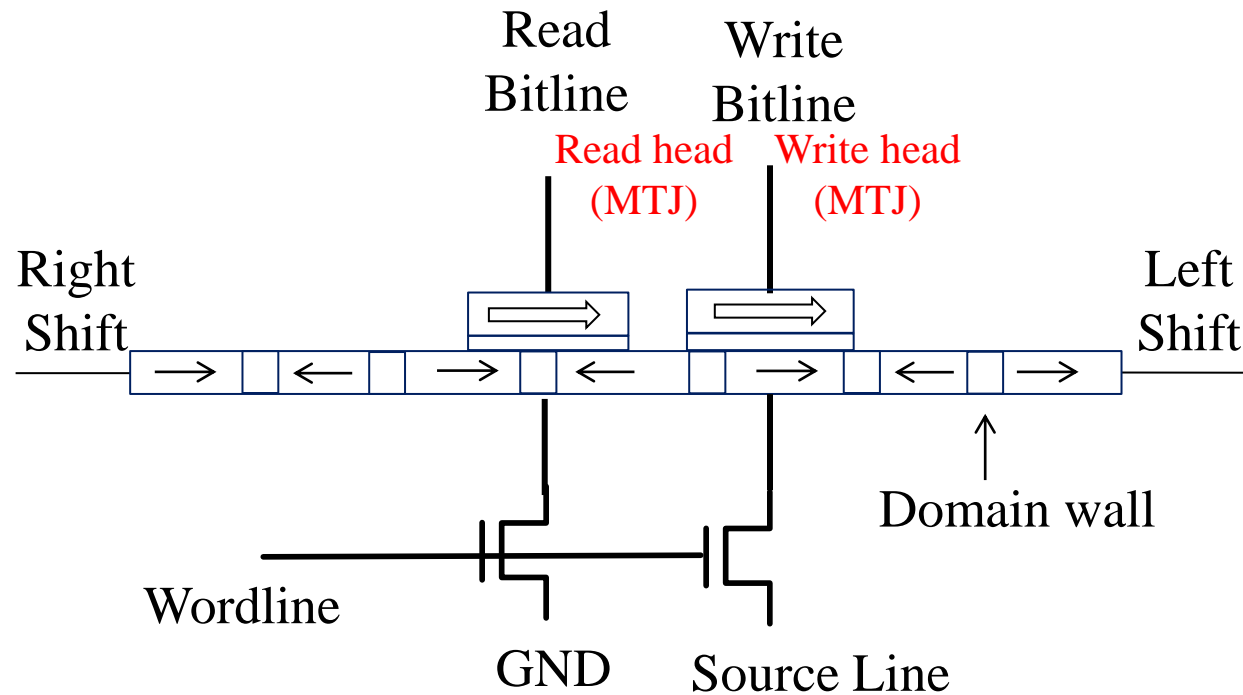
- Magnetic Tunnel Junction (MTJ) as Storage element
- MTJ consists of free (FL) and pinned (PL) magnetic layer
- Bits stored as resistance state
- Magnetic Orientation
 - Data “0”: Parallel (Low resistance)
 - Data “1”: Anti-parallel (High resistance)



Domain Wall Memory

- DWM Features

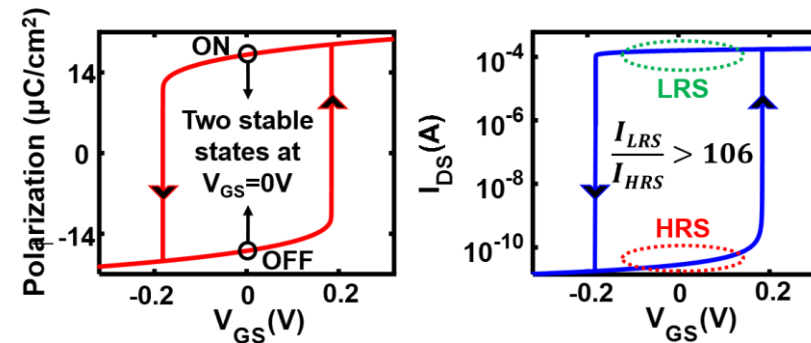
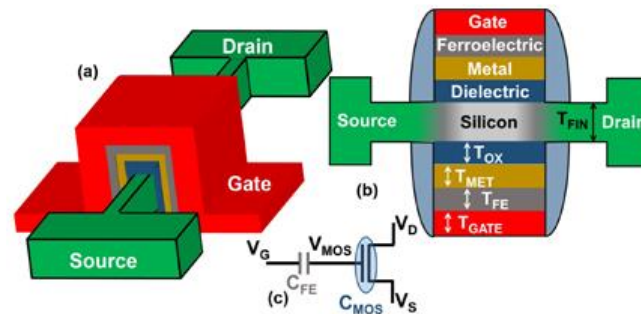
- Three components: Read MTJ, Write MTJ, Nanowire
- Bits are stored in nanowire that acts like a shift register
- Access mechanism is serial



NVM: Ferroelectric FET (FeFET)

- FeFET features

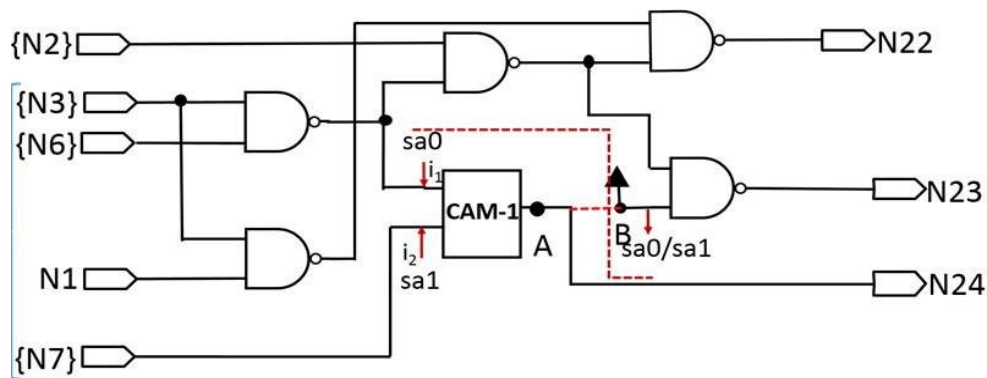
- Ferroelectric (FE) layer between metal gate and dielectric layer
- Stores data as polarization state (+ve or -ve) of FE layer
- Inherent 3-terminal structure allows isolation of read and write ports
- If +ve $V_{GS} >$ gate critical voltage \rightarrow polarization switches to positive



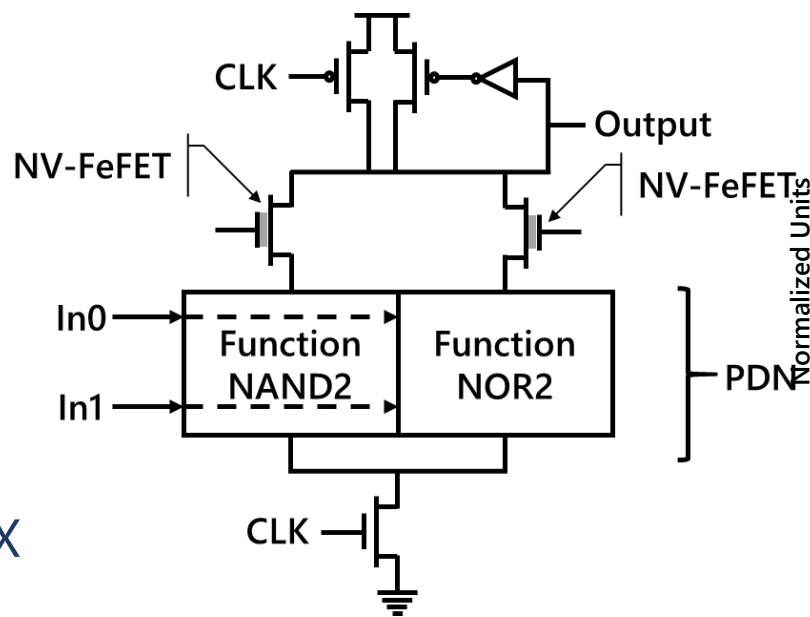
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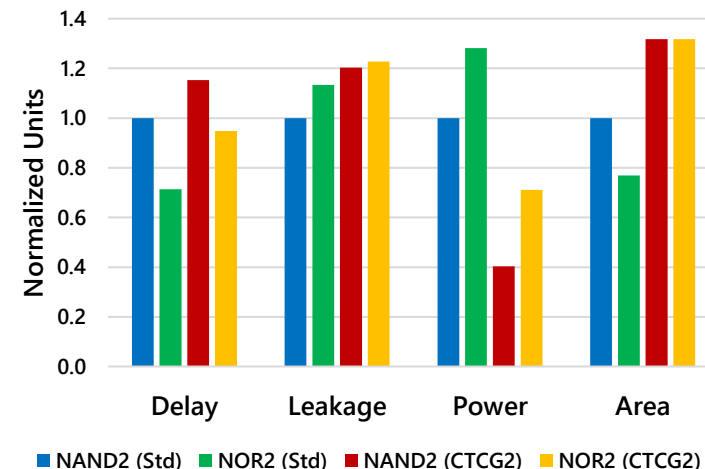
Exploiting Persistence-Obfuscation



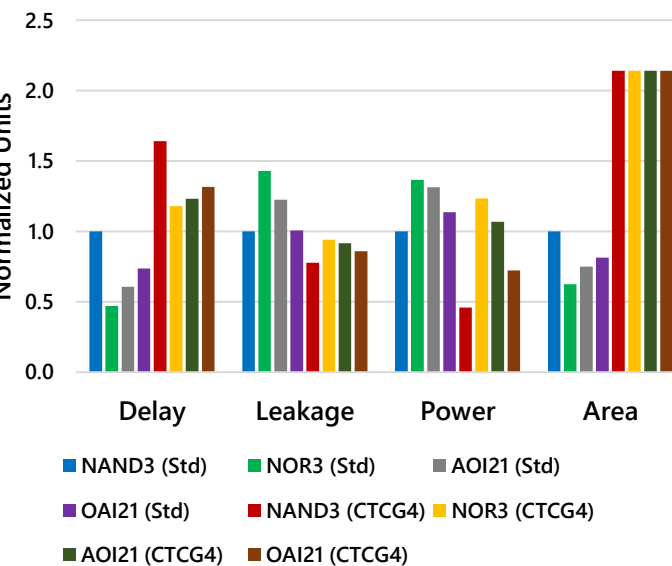
- Average delay overhead: 1.7X
- Average leakage overhead: 0.9X
- Average total power overhead: 0.6X
- Average area overhead: 2.3X



Comparative Analysis of CTCG2 (FeFET)

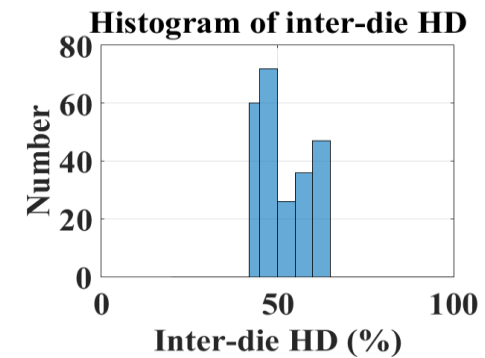
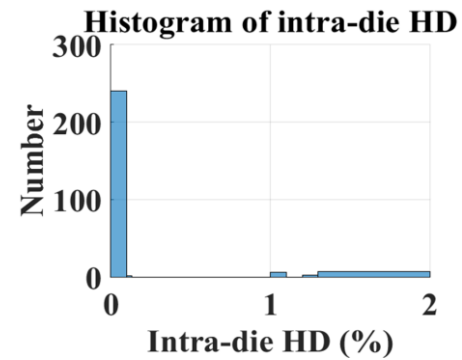
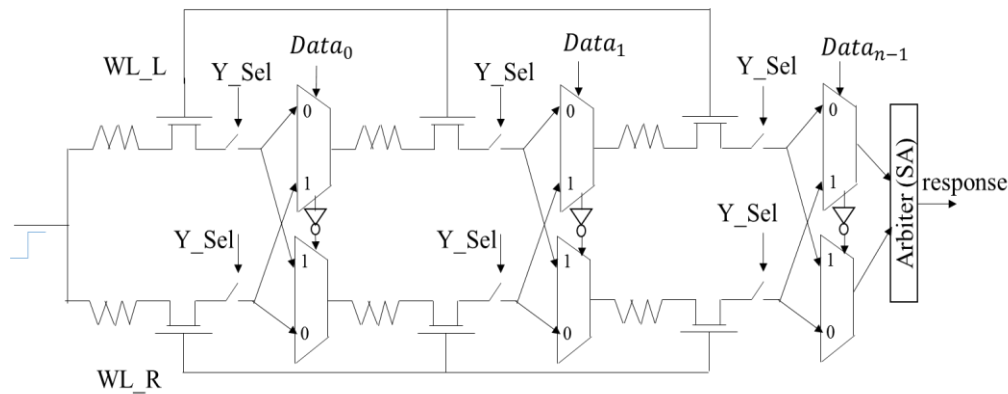


Comparative Analysis of CTCG4 (FeFET)



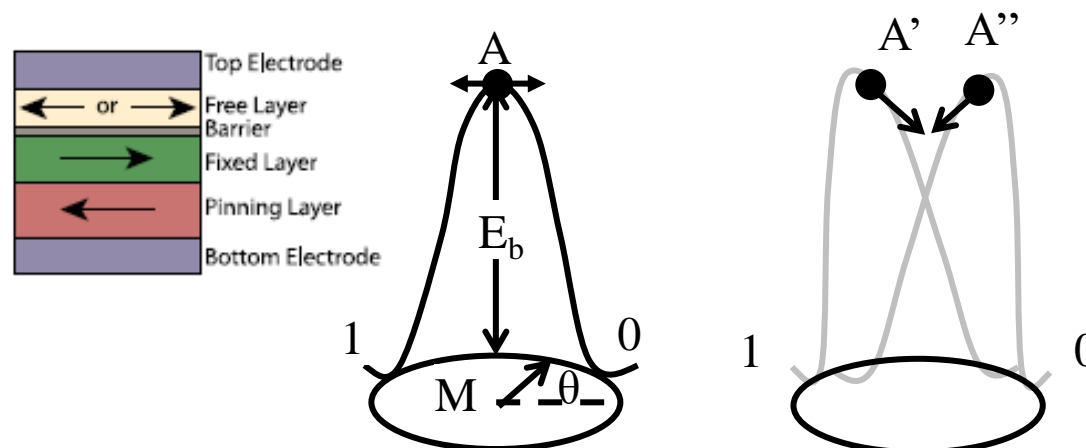
Exploiting Variations- Physically Unclonable Functions

- Design
 - PV in emerging NVM
 - RRAM based design using RC signal delay to generate PUF response



MRAM PUF

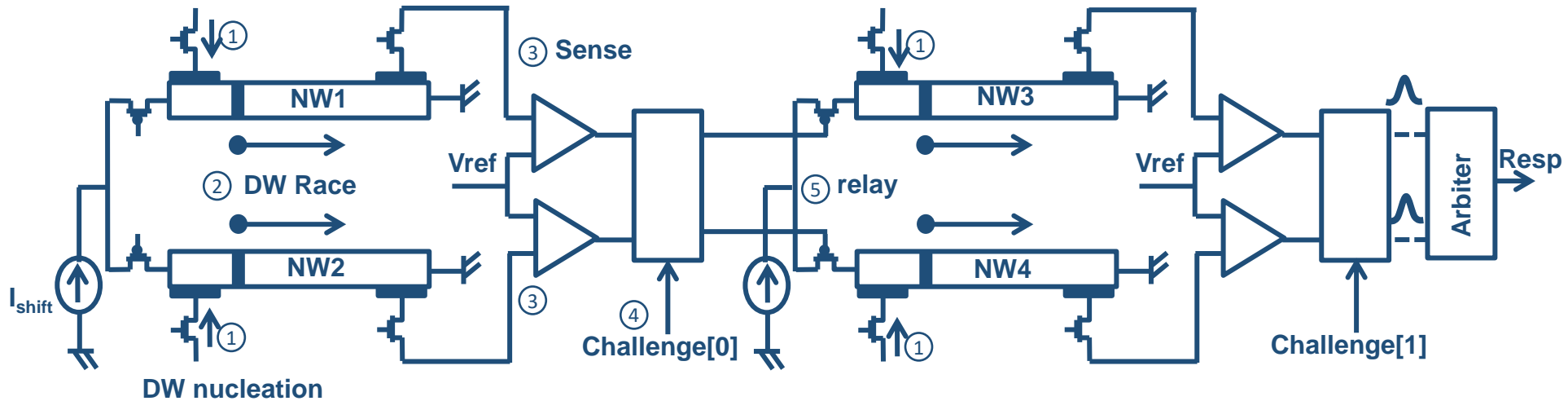
- Employs random initialization of the MTJ due to physical variations in the MTJ
- Variations create random tilt of energy barrier
- MTJ free layer is prone to prefer certain initial orientation much similar to SRAM PUF
- Intra-die HD of 0.0225 and an entropy of 0.99
- Decreasing the aspect ratio at constant volume and increasing the volume at constant aspect ratio is proposed to increase the tilt angle variation and enhance the stability of the PUF



PUF Types	\mathcal{D}_{intra}	\mathcal{D}_{inter}	$\rho(Y^n) \leq$	area (μm^2)
SRAM	0.078	0.49	0.94	51.99
Latch	0.26	0.3	0.71	531.25
D flip-flop	0.19	0.39	0.81	765.63
Arbiter	0.07	0.46	0.5-0.9	690.56
Ring Oscillator	0.099	0.46	0.86	7774.2
Memristor *	-	$\simeq 0.5$	-	-
STT-PUF *	$\sim 10\text{e-}6$	$\simeq 0.5$	0.985	6.79
MRAM	0.0225	0.47	0.99	6.74

Das, Jayita, Kevin Scott, Srinath Rajaram, Drew Burgett, and Sanjukta Bhanja. "MRAM PUF: A Novel Geometry Based Magnetic PUF With Integrated CMOS." (2015).

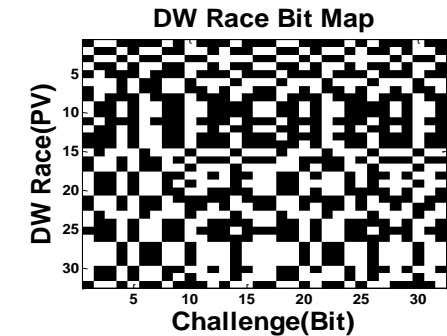
DWM-Relay PUF



- Operation of relay-PUF

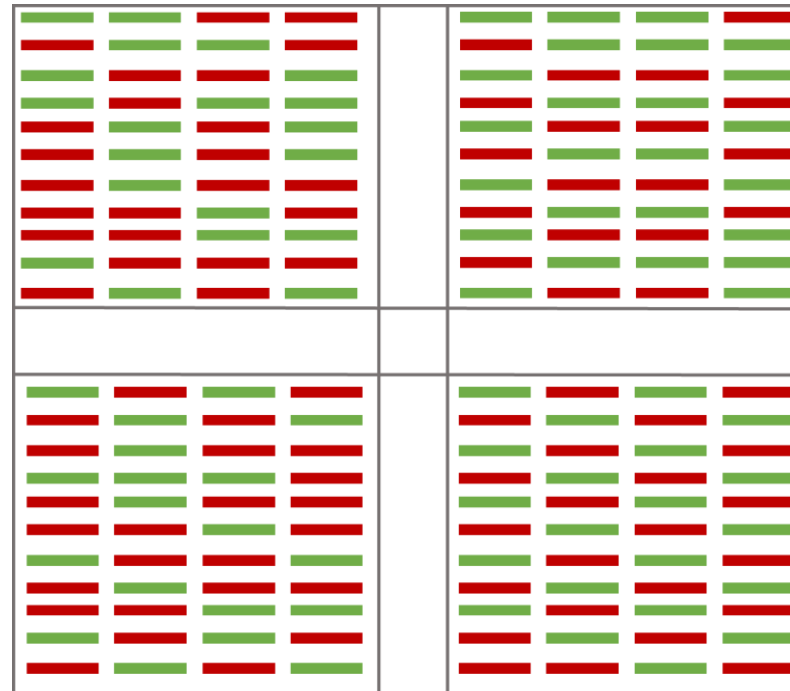
- DW nucleation
- Race
- Sense
- Relay
- Race...

- Variation in DW velocity due to variation is exploited
- Hamming distance=50%

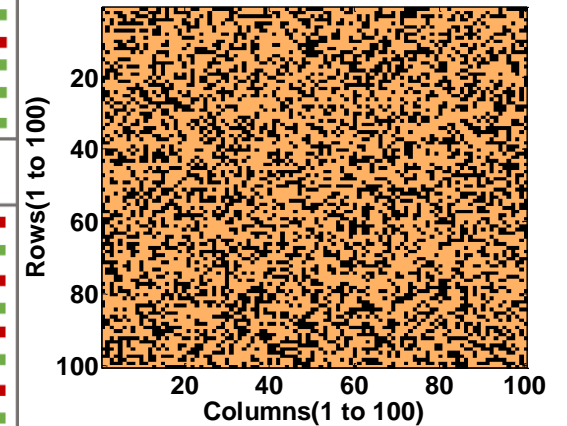


Memory PUF

- DW is raced in memory array (pinned: '0' (red), remaining: '1' (green))
- Uneven number of '0's and '1's at high voltage
- Temperature variation changes response
- Hamming distance is ~44%

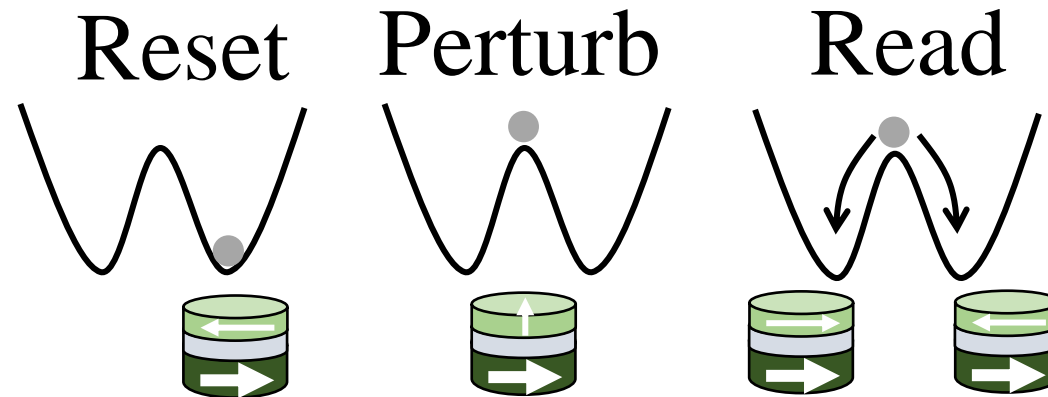


Memory map for a Typical Chip under PV



Spintronic TRNG

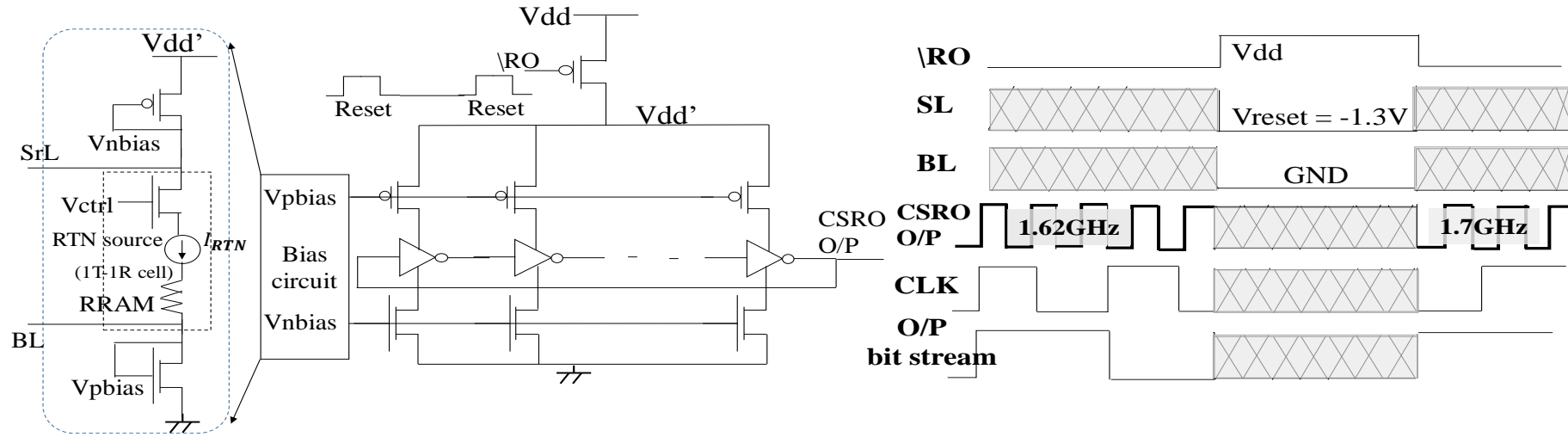
- Key ideas:
 - Reset the MTJ to AP state
 - Excite the free layer of the MTJ to the bifurcation point by applying a current pulse
 - Magnetization settle in random state due to thermal noise
 - To improve randomness and kill correlation bits are XOR'ed with each other
- Reset pulse is detrimental to MTJ reliability
- Sharing of reset and sense circuit makes sense MTJ susceptible to read disturb



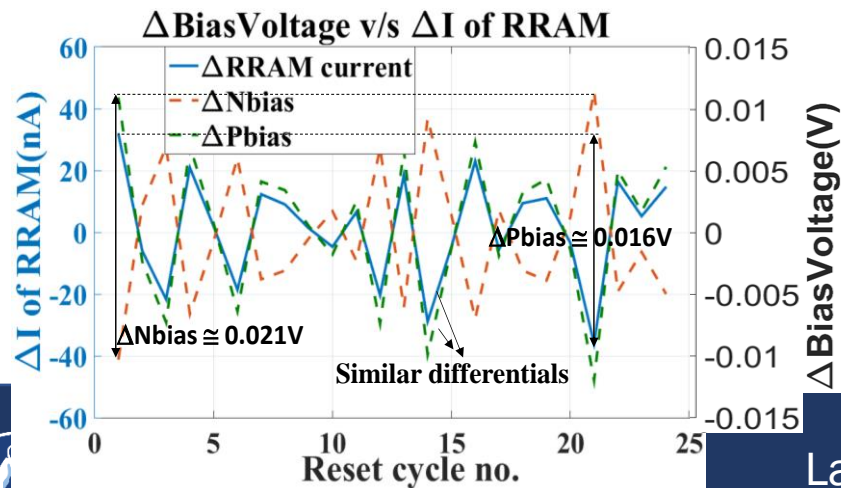
Choi, Won Ho, L. V. Yang, Jongyeon Kim, Abhishek Deshpande, Gyuseong Kang, Jian-ping Wang, and Chris H. Kim. "A Magnetic Tunnel Junction based True Random Number Generator with conditional perturb and real-time output probability tracking." In Electron Devices Meeting (IEDM), 2014 IEEE International, pp. 12-5. IEEE, 2014.

RRAM TRNG

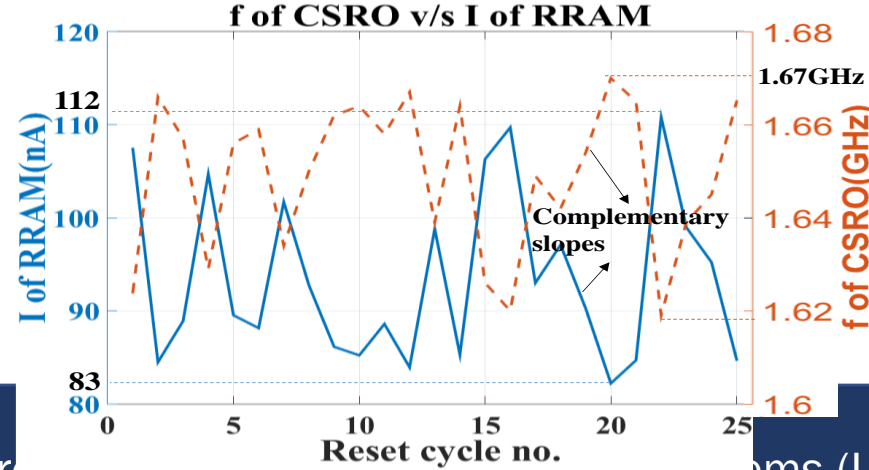
- RTN to generate random bit strings



Bias voltage differentials

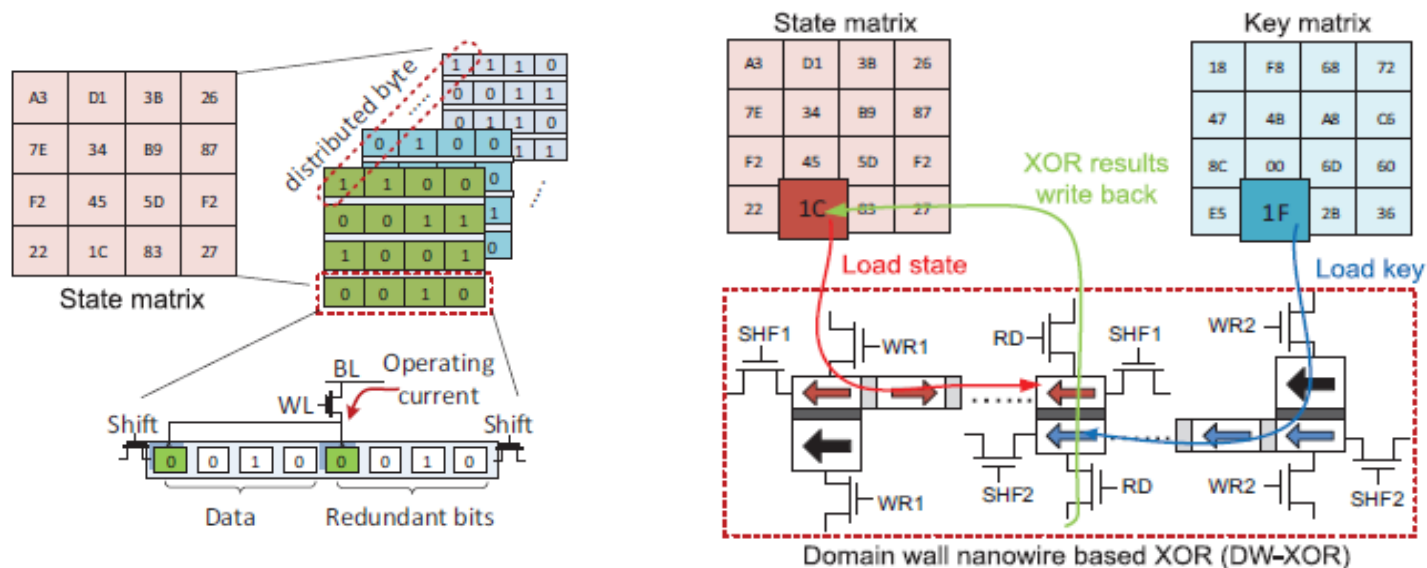


Frequency of CSRO oscillations



Spintronic Encryption Engine

- SubByte: The DW-based Look-Up Table (LUT) is used to save leakage power
- ShiftRows: To mimic cyclic rotation in nanowire, redundant bits are employed in DW nanowire
- MixColumns: multiplication by shift and addition. For addition domain wall XOR gate is employed
- AddRoundKey: This step XORs the SM with the round key



] Wang, Yuhao, Hao Yu, Dennis Sylvester, and Pingfan Kong. "Energy efficient in-memory aes encryption based on nonvolatile domain-wall nanowire." In Design, Automation and Test in Europe Conference and Exhibition (DATE), 2014, pp. 1-4. IEEE, 2014.

Open Research Problems

- Various new flavors of devices
 - SOT-MRAM
 - PMA-MTJ
 - Skyrmionic memory
- Application areas of hardware primitives
 - Data non-repudiation
 - System security issues e.g., buffer overflow
 - Machine learning

Conclusions

- Hardware supply chain presents several new attack surfaces
- Conventional CMOS technologies offer limited randomness, variations and noise sources
- Emerging NVMs possess novel ingredients suitable for security
- We reviewed multiple techniques and their security applications
- We also covered open problems in the area

Thank you!

- Acknowledgements

- Collaborators: Anupam Chattopadhyay, Shivam Bhasin, Jongsun Park, Rashmi Jha

